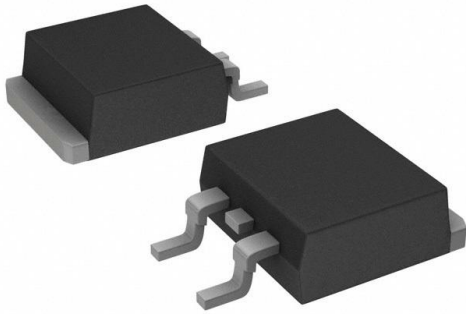


FQB6N80TM Datasheet

www.digi-electronics.com



<https://www.DiGi-Electronics.com>

DiGi Electronics Part Number	FQB6N80TM-DG
Manufacturer	onsemi
Manufacturer Product Number	FQB6N80TM
Description	MOSFET N-CH 800V 5.8A D2PAK
Detailed Description	N-Channel 800 V 5.8A (Tc) 3.13W (Ta), 158W (Tc) Surface Mount TO-263 (D2PAK)



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

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Purchase and inquiry

Manufacturer Product Number:

FQB6N80TM

Series:

QFET®

FET Type:

N-Channel

Drain to Source Voltage (Vdss):

800 V

Drive Voltage (Max Rds On, Min Rds On):

10V

Vgs(th) (Max) @ Id:

5V @ 250µA

Vgs (Max):

±30V

FET Feature:

-

Operating Temperature:

-55°C ~ 150°C (Tj)

Supplier Device Package:

TO-263 (D2PAK)

Base Product Number:

FQB6N80

Manufacturer:

onsemi

Product Status:

Obsolete

Technology:

MOSFET (Metal Oxide)

Current - Continuous Drain (Id) @ 25°C:

5.8A (Tc)

Rds On (Max) @ Id, Vgs:

1.950hm @ 2.9A, 10V

Gate Charge (Qg) (Max) @ Vgs:

31 nC @ 10 V

Input Capacitance (Ciss) (Max) @ Vds:

1500 pF @ 25 V

Power Dissipation (Max):

3.13W (Ta), 158W (Tc)

Mounting Type:

Surface Mount

Package / Case:

TO-263-3, D2PAK (2 Leads + Tab), TO-263AB

Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8541.29.0095

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99



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FQB6N80

N-Channel QFET[®] MOSFET

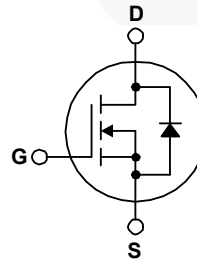
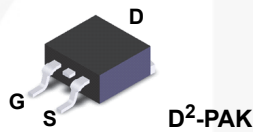
800 V, 5.8 A, 1.95 Ω

Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

Features

- 5.8 A, 800 V, $R_{DS(on)} = 1.95 \Omega$ (Max.) @ $V_{GS} = 10 V$, $I_D = 2.9 A$
- Low Gate Charge (Typ. 31 nC)
- Low Crss (Typ. 14 pF)
- 100% Avalanche Tested
- RoHS Compliant



Absolute Maximum Ratings $T_C = 25^\circ C$ unless otherwise noted.

Symbol	Parameter	FQB6N80TM	Unit
V_{DSS}	Drain-Source Voltage	800	V
I_D	Drain Current - Continuous ($T_C = 25^\circ C$) - Continuous ($T_C = 100^\circ C$)	5.8	A
		3.67	A
I_{DM}	Drain Current - Pulsed (Note 1)	23.2	A
V_{GSS}	Gate-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	680	mJ
I_{AR}	Avalanche Current (Note 1)	5.8	A
E_{AR}	Repetitive Avalanche Energy (Note 1)	15.8	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.0	V/ns
P_D	Power Dissipation ($T_A = 25^\circ C$) *	3.13	W
	Power Dissipation ($T_C = 25^\circ C$)	158	W
	- Derate above $25^\circ C$	1.27	W/ $^\circ C$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ C$
T_L	Maximum lead temperature for soldering, 1/8" from case for 5 seconds.	300	$^\circ C$

Thermal Characteristics

Symbol	Parameter	FQB6N80TM	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.79	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Minimum Pad of 2-oz Copper), Max.	62.5	
	Thermal Resistance, Junction to Ambient (*1 in ² Pad of 2-oz Copper), Max.	40	

FQB6N80 — N-Channel QFET[®] MOSFET

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQB6N80TM	FQB6N80	D ² -PAK	Tape and Reel	330 mm	24 mm	800 units

Electrical Characteristics

T_C = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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Off Characteristics

BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	800	--	--	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C	--	0.9	--	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 800 V, V _{GS} = 0 V	--	--	10	μA
		V _{DS} = 640 V, T _C = 125°C	--	--	100	μA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V	--	--	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V	--	--	-100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	3.0	--	5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 2.9 A	--	1.5	1.95	Ω
g _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 2.9 A	--	5.9	--	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz	--	1150	1500	pF
C _{oss}	Output Capacitance		--	125	160	pF
C _{rss}	Reverse Transfer Capacitance		--	14	18	pF

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	V _{DD} = 400 V, I _D = 5.8 A, R _G = 25 Ω	--	30	70	ns	
t _r	Turn-On Rise Time		--	70	150	ns	
t _{d(off)}	Turn-Off Delay Time		(Note 4)	--	65	140	ns
t _f	Turn-Off Fall Time		(Note 4)	--	45	100	ns
Q _g	Total Gate Charge	V _{DS} = 640 V, I _D = 5.8 A, V _{GS} = 10 V	--	31	--	nC	
Q _{gs}	Gate-Source Charge		(Note 4)	--	7.1	--	nC
Q _{gd}	Gate-Drain Charge		(Note 4)	--	15	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

I _S	Maximum Continuous Drain-Source Diode Forward Current	--	--	5.8	A	
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current	--	--	23.2	A	
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 5.8 A	--	--	1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 5.8 A,	--	650	--	ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs	--	5.7	--	μC

Notes:

1. Repetitive rating : pulse-width limited by maximum junction temperature.
2. L = 38 mH, I_{AS} = 5.8 A, V_{DD} = 50 V, R_G = 25 Ω, starting T_J = 25°C.
3. I_{SD} ≤ 5.8 A, di/dt ≤ 200 A/μs, V_{DD} ≤ BV_{DSS}, starting T_J = 25°C.
4. Essentially independent of operating temperature.

Typical Characteristics

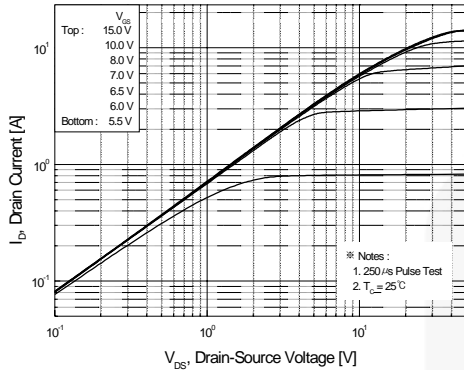


Figure 1. On-Region Characteristics

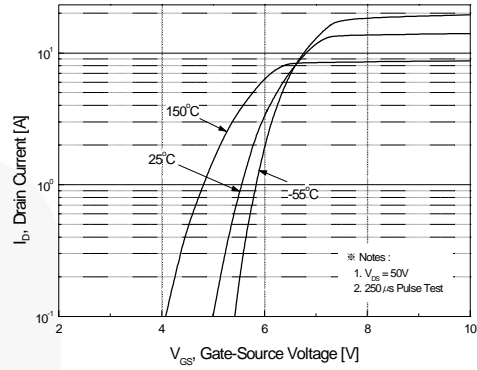


Figure 2. Transfer Characteristics

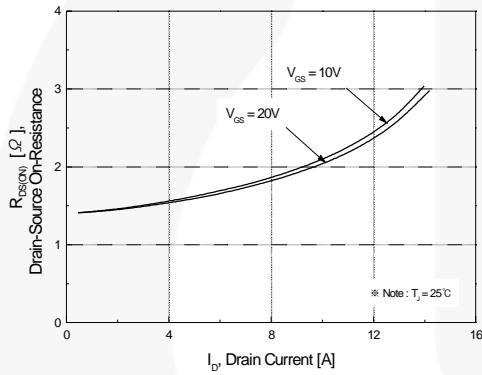


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

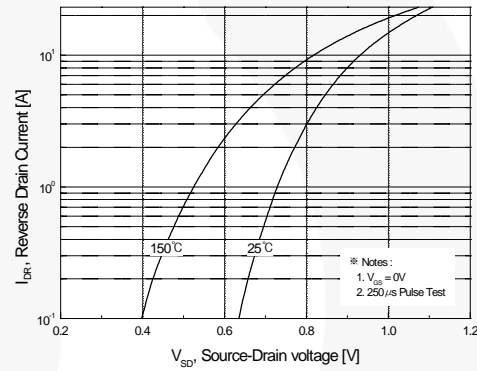


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

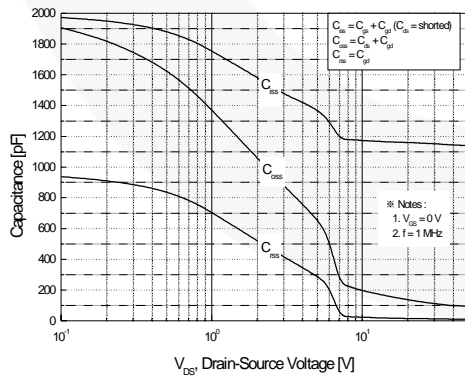


Figure 5. Capacitance Characteristics

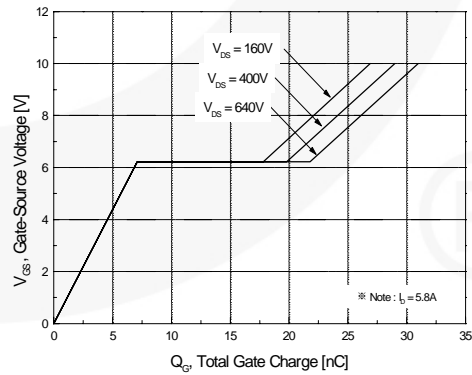


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

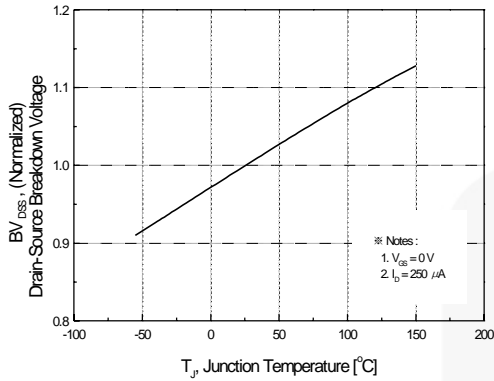


Figure 7. Breakdown Voltage Variation vs Temperature

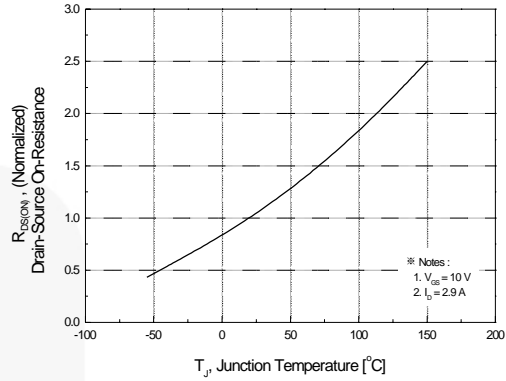


Figure 8. On-Resistance Variation vs Temperature

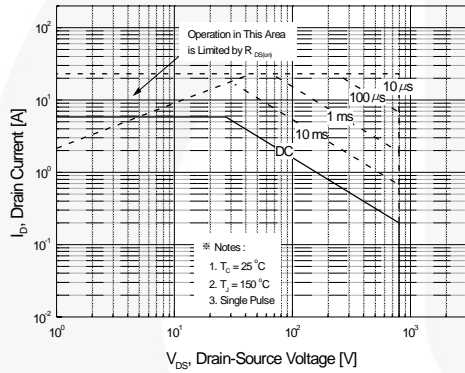


Figure 9. Maximum Safe Operating Area

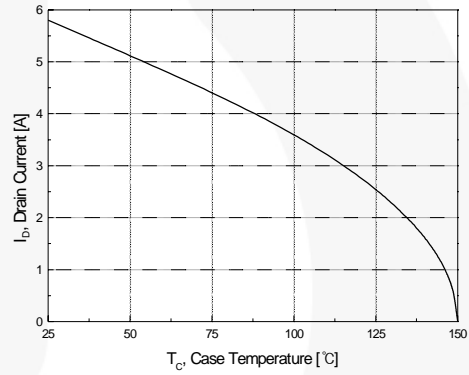


Figure 10. Maximum Drain Current vs Case Temperature

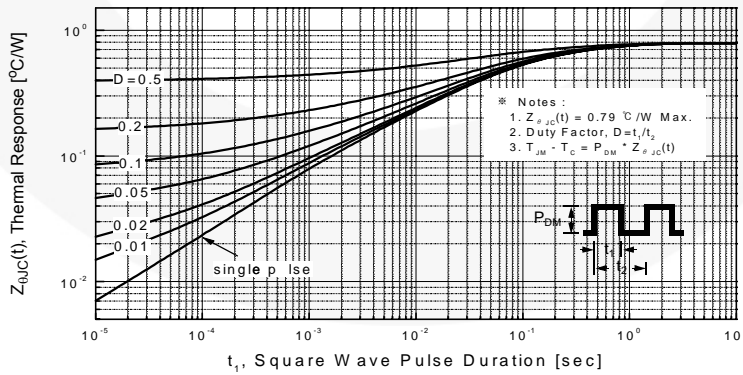


Figure 11. Transient Thermal Response Curve

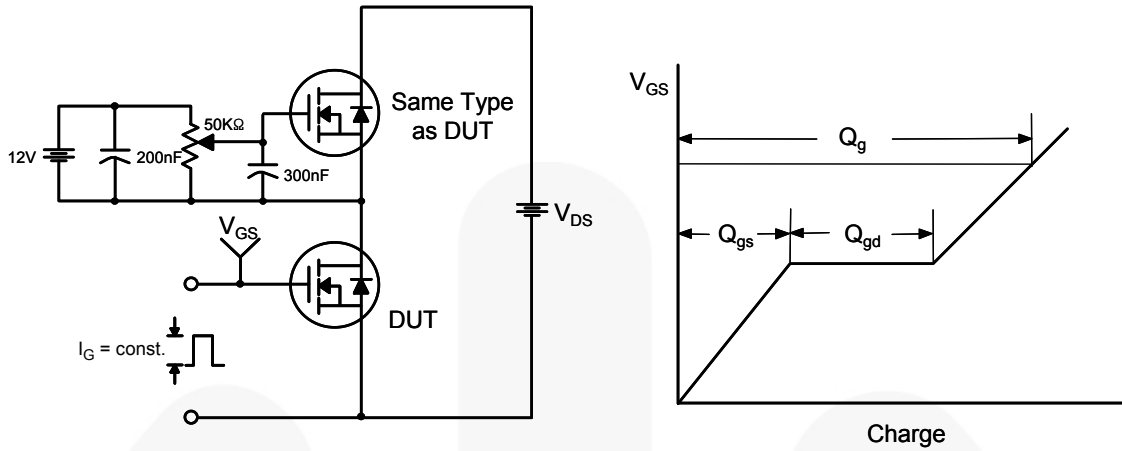


Figure 12. Gate Charge Test Circuit & Waveform

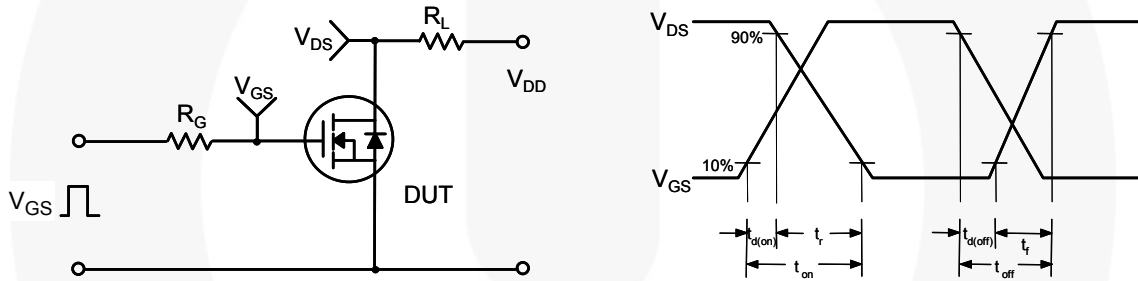


Figure 13. Resistive Switching Test Circuit & Waveforms

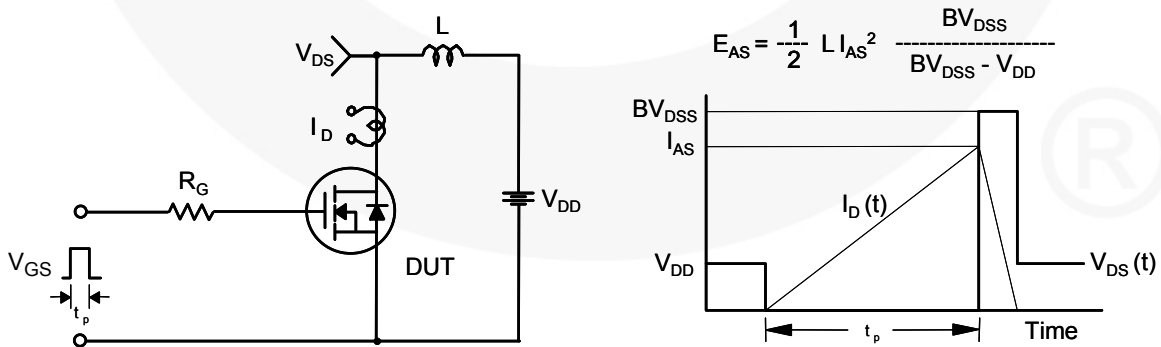


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

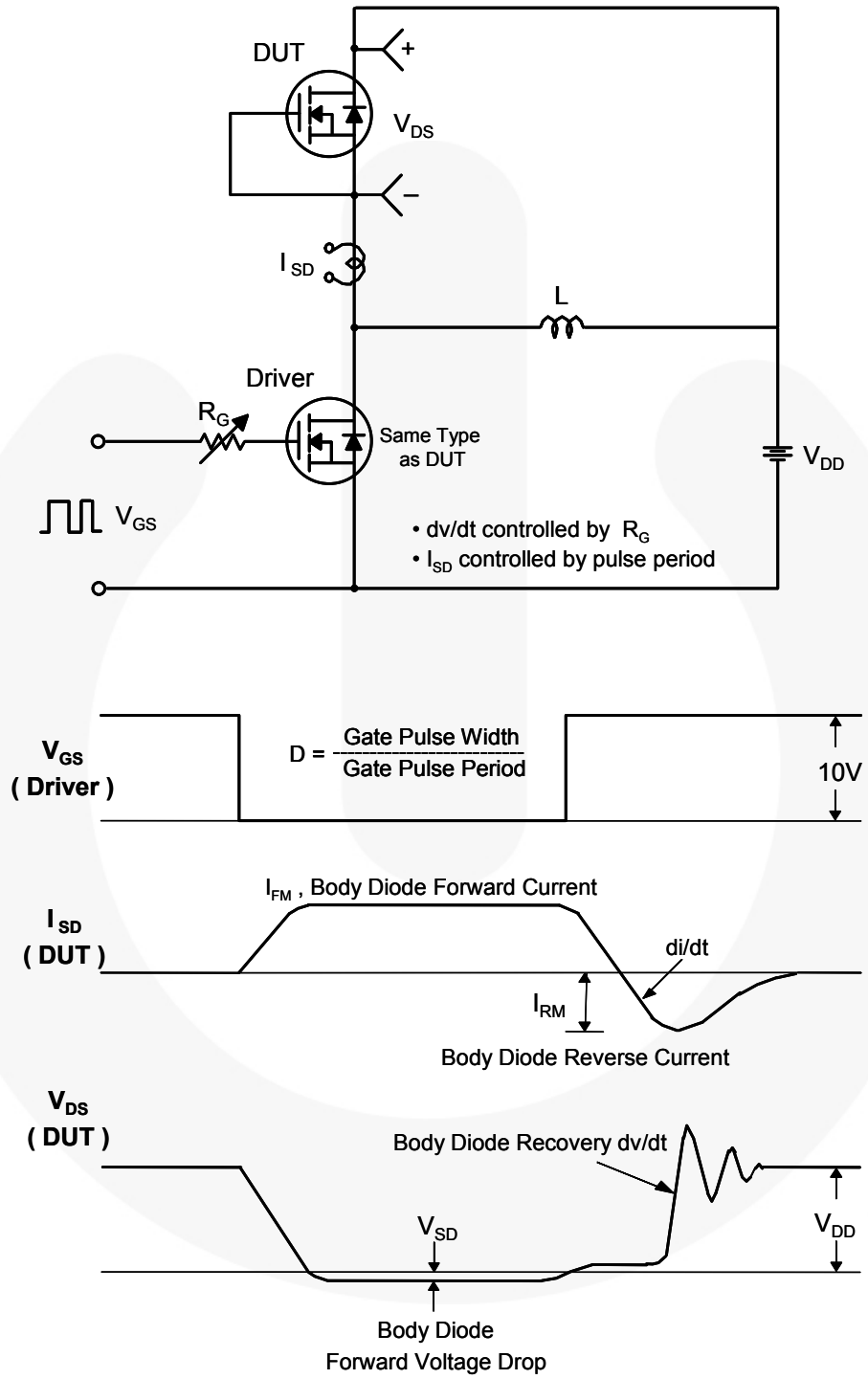


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions

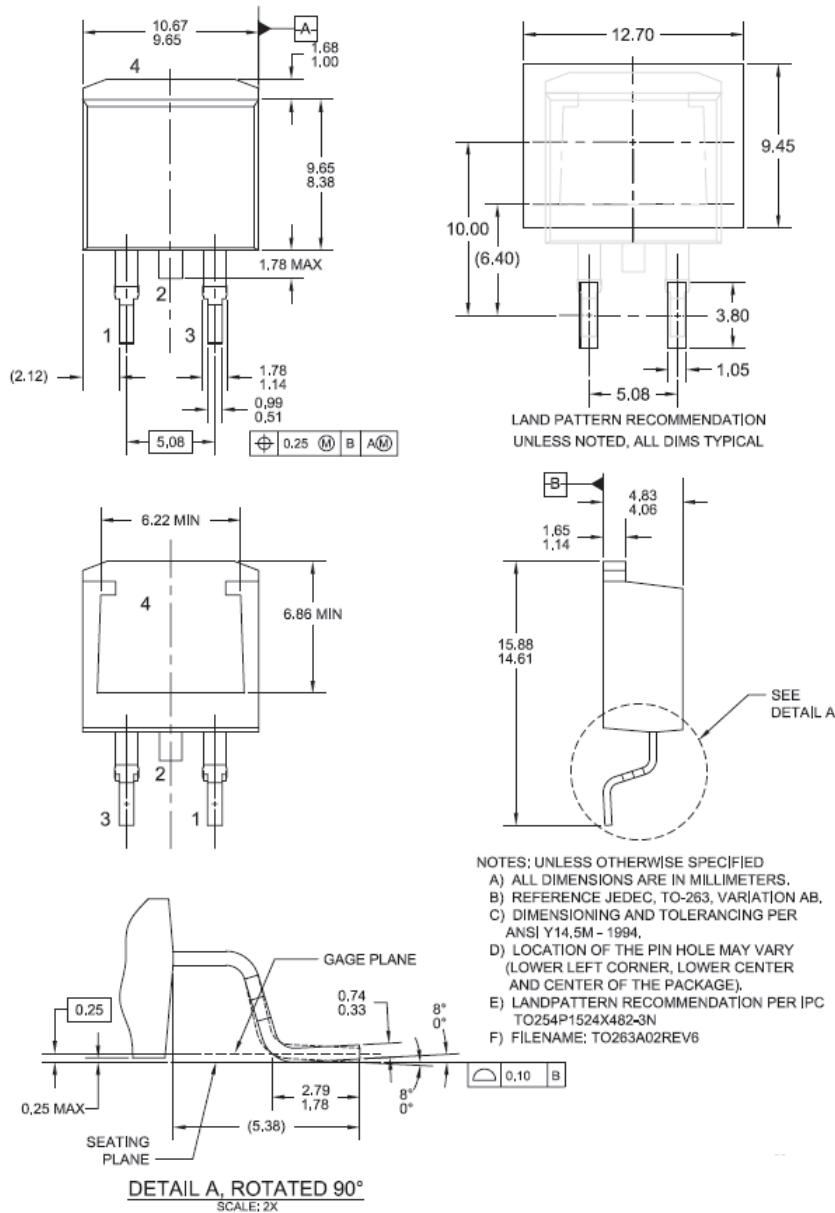


Figure 16. TO263 (D²PAK), Molded, 2-Lead, Surface Mount

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No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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